



FINAL POLISHING SYSTEM - 3 -

SAITAMA SEIKI CO., LTD.
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<Work 1> Removal of seediness

[Specifications]

Model	Speed	Weight	Pad size	Paper size
U-51	8500rpm	480g	30mm	32mm

STANDARD ACCESSORIES:

30mm Velcro Pad Base & 30mm Glue-on Disc

[Applications]

- *Removal of seeding, runs, dust chips, etc. on the painted surface of automobile or motorcycle body and other components.
- *Removal of dust chips for baking-painted electric appliances.

[Features]

- *Removal can be made at the minimum area.
- *Double action prevents deep grinding, that saves the polishing time for finishing work.

MODEL U-51



<Work 2> Polishing

[Specifications]

Model	Speed	Weight	Pad size	Buffer size
U-53SP	10000rpm	940g	72mm	85mm

STANDARD ACCESSORY:

72mm Velcro Pad

[Applications]

- *All-in-one finishing polisher.
- *to be used with 3M buffing pad (PN02637)

[Features]

- *Compact & well-balanced.
- *Orbit diameter is 12mm: high efficiency: short polishing time.
- *Double action: remove scratches and white fog.

MODEL U-53SP

